

IN THE ABSTRACT

Please amend the Abstract of the Disclosure as indicated below.

A method is disclosed of temperature compensation for measurement of a temperature sensitive parameter of semiconductor IC chips, particularly temperature compensation for a maximum frequency measurement (Fmax) and speed sort/categorization of semiconductor IC chips. The method ~~comprises~~ includes determining a change of a temperature sensitive parameter of the chip with temperature; measuring the temperature sensitive parameter of the chip during testing of the chip; measuring the chip temperature directly during or following the measurement of the temperature sensitive parameter; and determining an adjusted temperature sensitive parameter of the chip based upon the measured temperature sensitive parameter of the chip during testing, the measured chip temperature, and the determined change of the temperature sensitive parameter of the chip with temperature.